

IN THE CLAIMS

Please add claims 36 - 39.

Please amend claim 16 as follows:

1-10. (Cancelled)

11. (Previously Presented) An electronic module comprising:

a first and a second component with connections on connection sides of the components;
a wiring block with contact pads on its outer sides and with lines in its volume, the lines electrically connecting the contact pads on the outer sides to one another according to a circuit layout, the first component and the second component being arranged on different non-opposite outer sides of the wiring block and the connections being connected to the contact pads.

12. (Previously Presented) The electronic module according to claim 11, comprising wherein the lines comprise carbonized plastic.

13. (Previously Presented) The electronic module according to claim 11, comprising wherein the lines comprise nanoparticles with carbonized short-circuit paths between the nanoparticles.

14. (Previously Presented) The electronic module according to claim 11, comprising wherein the lines comprise anisotropically oriented nanoparticles.

15. (Previously Presented) The electronic module according to claim 11, comprising wherein the lines comprise carbonized plastic, the lines including nanoparticles with carbonized short-circuit paths between the nanoparticles, including comprising wherein the lines comprise anisotropically oriented nanoparticles.

Applicant: Michael Bauer et al.

Serial No.: 10/562,252

Filed: July 5, 2006

Docket No.: I431.140.101/FIN40PCT/US

Title: ELECTRONIC MODULE AND METHOD FOR THE PRODUCTION THEREOF

16. (Currently Amended) An electronic module comprising:

a first and a second component with connections on connection sides of the components; a wiring block with contact pads on its outer sides and with lines in its volume, the lines electrically connecting the contact pads on the outer sides to one another according to a defined circuit layout, the first component and the second component being arranged on different outer sides of the wiring block and the connections being connected to the contact pads;

wherein the wiring block includes a plastic[[e]] volume through which the lines extend, and includes at least six outer sides configured for population with electronic devices or components, such that line routing through the wiring block is configurable for three-dimensional wiring between contact pads.

17. (Previously Presented) The electronic module according to claim 16, comprising the wiring block including vertical line routing, horizontal line routing, or line routing at different solid angles, thereby achieving reduced length wiring paths and reducing propagation time delays within the wiring block.

18. (Previously Presented) The electronic module according to claim 16, comprising wherein a configuration of the line routing is three-dimensional.

19. (Previously Presented) The electronic module according to claim 18, comprising wherein the line routing is configured as a spiral.

20. (Previously Presented) The electronic module according to claim 16, comprising wherein the line routing includes one or more lines configured as a sheet.

21. (Previously Presented) The electronic module according to claim 16, comprising wherein routing lines are configured as an electrical component.

Applicant: Michael Bauer et al.

Serial No.: 10/562,252

Filed: July 5, 2006

Docket No.: I431.140.101/FIN40PCT/US

Title: ELECTRONIC MODULE AND METHOD FOR THE PRODUCTION THEREOF

22. (Previously Presented) The electronic module according to claim 21, wherein the electrical component is a passive electrical component.

23. (Previously Presented) The electronic module according to claim 21, wherein the electrical component is an inductive component.

24. (Previously Presented) The electronic module according to claim 21, wherein the electrical component is a capacitive component.

25. (Previously Presented) The electronic module according to claim 16, comprising wherein the lines comprise carbonized plastic.

26. (Previously Presented) The electronic module according to claim 16, comprising wherein the lines comprise nanoparticles with carbonized short-circuit paths between the nanoparticles.

27. (Previously Presented) The electronic module according to claim 16, comprising wherein the lines comprise anisotropically oriented nanoparticles.

28. (Withdrawn) A device for producing an electronic module, comprising:
a casting mold for the introduction of plastic;
two focusable energy sources with an orienting device configured for guiding and superposing the focus regions of the energy sources for forming lines of the wiring block to be produced in the volume of the plastic to be introduced; and
at least one casting device for the continuous or layer-by-layer filling of the casting mold with plastic with the formation of lines in the envisaged volume of the wiring block.

29. (Withdrawn) The device according to claim 28, comprising wherein the focusable energy sources are laser apparatuses.

30. (Withdrawn) The device according to claim 28, comprising wherein the device comprises a microprocessor for controlling the energy sources.

31. (Withdrawn) A method for producing an electronic module having two components on different outer sides of the wiring block, the wiring block comprising electrical contact pads, the method comprising:

introduction of plastic into a casting mold for the production of a plastic blank block;

partial carbonization of the plastic and/or partial agglomeration of nanoparticles in the plastic blank block to form lines of a wiring block according to a predetermined circuit layout by means of radiating in energy of two focused and guided energy beams from energy sources;

removal of the wiring block from the casting mold;

application of contact pads at piercing points of the lines on the outer sides; and

application of two components with their connections on different and non opposite outer sides of the wiring block.

32. (Withdrawn) The method according to claim 31, comprising wherein firstly at least one plastic layer with lines is produced and afterward further plastic layers arranged on the first layer are realized, lines being produced within the layers and from layer to layer by carbonization of the plastic and/or by agglomeration of nanoparticles in the respective plastic layer.

33. (Withdrawn) The method according to claim 31, comprising effecting the introduction of energy for forming lines by means of microwave excitation, by means of electromagnetic radiation or by means of ultrasonic radiation.

34. (Withdrawn) The method according to claim 31, comprising wherein firstly at least one plastic layer with lines is produced and afterward further plastic layers arranged on the first layer

are realized, lines being produced within the layers and from layer to layer by carbonization of the plastic and/or by agglomeration of nanoparticles in the respective plastic layer, and comprising effecting the introduction of energy for forming lines by means of microwave excitation, by means of electromagnetic radiation or by means of ultrasonic radiation.

35. (Withdrawn) An electronic module comprising:

means for providing a first and a second component with connections on connection sides of the components;

a wiring block with contact pads on its outer sides and with lines in its volume, the lines electrically connecting the contact pads on the outer sides to one another according to a circuit layout, the first component and the second component means being arranged on different non-opposite outer sides of the wiring block means and the connections being connected to the contact pads.

36. (New) The electronic module according to claim 11, comprising wherein the wiring block comprise a plastic.

37. (New) The electronic module according to claim 36, comprising wherein the wiring block comprise plastic with nanoparticles.

38. (New) The electronic module according to claim 11, comprising wherein the wiring block includes at least six outer sides.

39. (New) The electronic module according to claim 11, comprising wherein the contacts of the first and second components are flip-chip contacts.